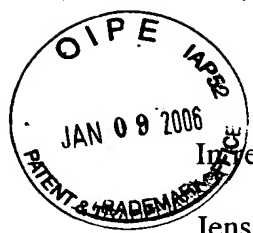


IFW



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventive application of:

Group Art Unit: 1732

Jens-Christian D. Meiners et al.

Examiner: Angela y. Ortiz

Serial No.: 10/672,254

Filed: September 26, 2003

For: PACKAGING TECHNIQUE FOR ELASTOMERIC
MICROFLUIDIC CHIPS AND MICROFLUIDIC DEVICE
PREPARED THEREBY

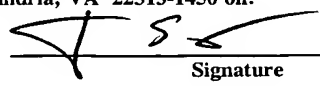
Attorney Docket No.: UOM 0275 PUSP

AMENDMENT UNDER 37 C.F.R. § 1.111

Mail Stop Amendment
Commissioner for Patents
U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed October 5, 2005, please amend the
above-identified application as follows:

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8 (FIRST CLASS MAIL)		
I hereby certify that this paper, including all enclosures referred to herein, is being deposited with the United States Postal Service as first-class mail, postage pre-paid, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, U.S. Patent and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450 on:		
<u>January 5, 2006</u> Date of Deposit	<u>Michael S. Brodbine</u> Name of Person Signing	 Signature